



Floor finish

Flexible tile adhesive

12mm AmbiFlex® P12 Pipe

AmbiDeck® 18 board

Timber subfloor

Concrete subfloor

±18MM±

Low-profile build-up



Tile over directly



Lay on solid or timber floors



Speed of installation

System Overview

The AmbiDeck® 18 system really does give the best of both worlds – it provides a low-profile underfloor heating system, which incorporates an insulation layer and can be tiled directly onto. AmbiDeck® 18 consists of a high-density XPS insulation panel, 18mm thick.

The face of the panel is cement-coated, making it rigid and durable. It is grooved to take 12mm UFH pipework, with a radius return grooved into each panel, making the panel universal. Additional pipework channels can easily be routed/ grooved into the panel.

Key Features

- **High-Density XPS Insulation** - Excellent compressive strength and thermal performance
- **Fast Installation** - Lightweight panels allow quick fitting and reduced on-site time.
- **Low-profile** - Only 18mm total system build-up
- **Direct tiling** - Suitable for tiling directly over the system

AmbiFibre Pro Compound

AmbiDeck® 18 must be laid onto a flat, level subfloor, either concrete or timber-based. Over a concrete floor, we recommend adhering panels with flexible tile adhesive or DeckBond spray adhesive. Over a timber floor, we recommend securing the panels down with a minimum of 12 AmbiDeck® screws & washers per board, or alternatively with DeckBond spray adhesive.

Tiling can be laid directly over the system - we recommend priming the boards with a tiling primer and filling any gaps with flexible tiling adhesive. If laying carpet/vinyl/wooden floor, we recommend a minimum of 6 mm levelling compound over the top of AmbiDeck® 18.

PERFORMANCE SPECIFICATION

20°C ROOM TEMPERATURE AT MWT OF 45°C AND 0 TOG

| HEIGHT (MM) | WEIGHT (KG/M ²) | OUTPUT (W/M ²) |
|-------------|-----------------------------|----------------------------|
| 18 | 13 | 79 |

Tested in accordance with BS EN1264-2:2021